ACEPACK DRIVE WITH Gen3 SiC MOSFETs



Compact, high performance module for traction inverters



Combining the features of SiC Gen3 technology with an optimized compact design, ACEPACK DRIVE is ideal for HEV/EV traction inverters

ACEPACK DRIVE power modules have been specifically designed for satisfying the growing demand from automobile manufacturers for greater power ranges and higher efficiency in HEV/EV traction inverters.

Using the industry standard footprint, these readyto-use power modules reduce the design effort of the driving board and the time-to-market.

Thanks to the direct liquid-cooled base plate, ACEPACK DRIVE modules offer optimal thermal performance, and enhanced lifetime as a result of the sintering technology used as die attach, combined with the AMB substrates.

KEY FEATURES & BENEFITS

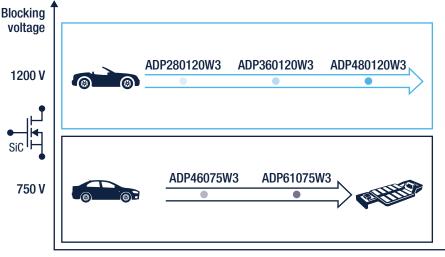
- 750 V and 1200 V breakdown voltages
- Extremely high power density and efficiency
- 175 °C maximum junction temperature
- Press fit connections
- AMB substrate and direct liquid-cooled base plate
- Unequaled R_{DS(on)}
- 4.2 kV DC 1 s isolation
- Dedicated NTC for each single substrate

KEY APPLICATIONS

Main inverter (electric traction):

- Light electric vehicles
- UAM
- Commercial & agriculture vehicles
- Trucks & buses
- E-motorbikes
- Sport cars

ACEPACK DRIVE power modules are based on the 3rd generation of SiC MOSFETs that offers optimal efficiency and performance. Furthermore, the incredibly high power density of the modules minimizes system room occupation and covers a power range from 175 to more than 300 kW at a voltage rating from 750 V to 1200 V.



Power

AC bus bar options available





Product portfolio

Part number	Breakdown Voltage (V)	R _{DS(on)} @ 25 °C (mΩ)	R _{DS(on)} @ 175 °C (mΩ)	Target power (kW)	Features
ADP280120W3	1200	3.8	6.5	180	Short tab
ADP360120W3		2.55	4.25	230	Short tab
ADP480120W3		1.9	3.35	300	Short tab
ADP480120W3-L					Long tab
ADP46075W3	750	1.6	2.6	175	Short tab
ADP61075W3		1.2	1.95	220	Short tab
ADP61075W3-L					Long tab



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